

## SPECIFICATION FOR APPROVAL

### 1/3W, 0805 Low Resistance Chip Resistor (Lead / Halogen free)

#### 1. Scope

This specification applies to 1.2mm x 2.0mm size 1/3W, fixe metal film chip resistors rectangular type for use in electronic equipment.

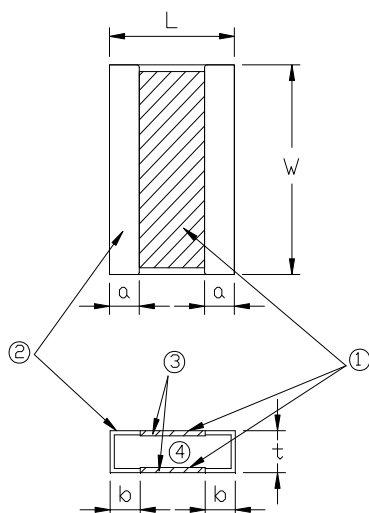
#### 2. Type Designation

RLW2012 — F — □□□□ □  
 (1) (2) (3) (4)

Where

- (1) Series No.
- (2) Power rating  
 $F = 1/3W$
- (3) Resistance value:  
 For example—  
 $R005 = 0.005 \Omega$
- (4) Resistance tolerance:  
 $F = \pm 1\%$   
 $G = \pm 2\%$   
 $J = \pm 5\%$

#### 3. Construction and Physical Dimensions



Code Letter	Dimensions (mm)
L	$1.3 \pm 0.20$
W	$2.0 \pm 0.20$
t	$0.50 \pm 0.20$
a	$0.35 \pm 0.15$
b	$0.35 \pm 0.15$

**NOTE:**

- ① Resistive element  
( under protection film )
- ② Electrode
- ③ Protection film
- ④ Substrate

Figure 1. Structure (No mark)

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## 4. Ratings

## 4-1 Specification

Power Rating*	1/3 W
Resistance Range	0.005Ω~0.030Ω
Resistance Tolerance	±1% , ±2% , ±5%
Temperature Coefficient of Resistance	0~200ppm/°C

Note\*:

Power Rating is based on continuous full load operation at rated ambient temperature of 70°C. For resistors operated at ambient temperature in excess of 70°C, the maximum load shall be derated in accordance with the following curve.

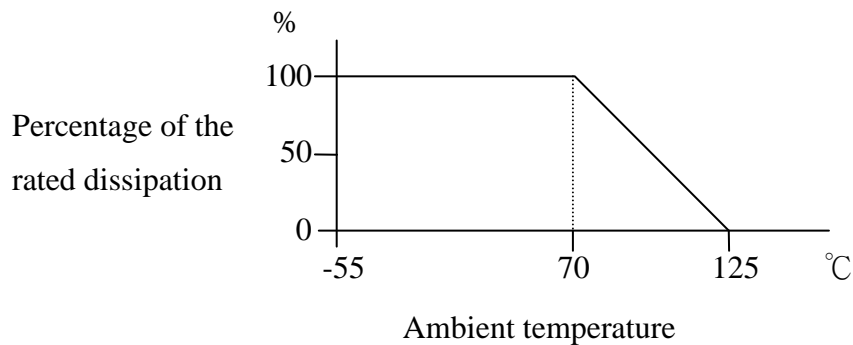


Figure 2 Derating Curve

## 4-2 Rated Voltage

The rated voltage shall be determined by the following expression.

$$V = \sqrt{P \times R}$$

Where V : Rated voltage (V)

R : Nominal resistance value (Ω)

P : Rated dissipation (W)

## 4-3 Operating and Storage Temperature Range

-55 to +125°C



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5. Characteristics

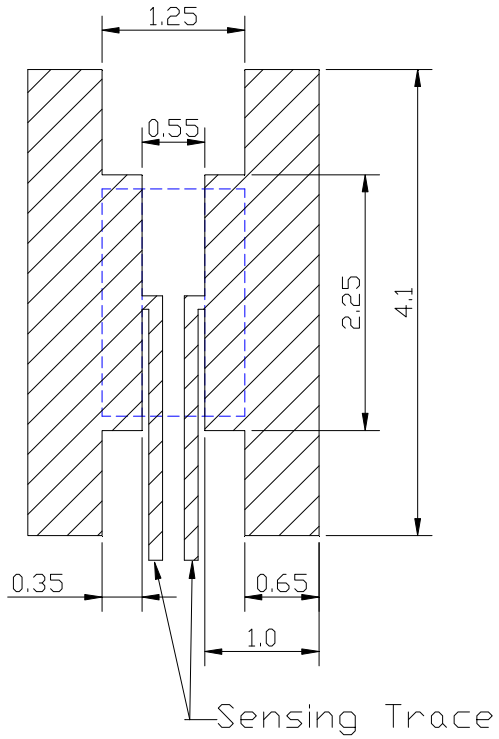
Test Item	Condition of Test	Requirements
Short Time Overload	5 * Rated power for 5 seconds Refer to JIS C 5201-1 4.13	$\Delta R : \pm (0.5\% + 0.0005\Omega)$ Without significant damage by flashover ( spark, arching ), burning or breakdown etc.
Insulation Resistance	The resistor shall be cramped in the metal block and tested , as shown below. Test voltage : $100 \pm 15V_{DC}$ for 1 minute Refer to JIS C 5201-1 4.6 Mounting condition G.	Between Electrode and Protection Film $100M\Omega$ or over Between Electrode and Substrate $1,000M\Omega$ or over
Voltage Proof	The voltage : $100V_{AC}$ (rms.) for 1 minute Refer to JIS C 5201-1 4.7	$\Delta R : \pm (1.0\% + 0.0005\Omega)$ Without damage by flashover, fire or breakdown, as shown below.
Thermal Shock	$-55 \sim 125^{\circ}C$ 5 cycles, 15 min at each extreme condition Refer to JIS C 5201-1 4.19	$\Delta R : \pm (1.0\% + 0.0005\Omega)$ Without distinct damage in appearance
Low Temperature Storage	Kept at $-55^{\circ}C$ , 1,000 hours Refer to JIS C 5201-1 4.23.4	$\Delta R : \pm (1.0\% + 0.0005\Omega)$ Without distinct damage in appearance
High Temperature Exposure	Kept at $125^{\circ}C$ for 1,000 hours Refer to JIS C 5201-1 4.23.2	$\Delta R : \pm (1.0\% + 0.0005\Omega)$ Without distinct damage in appearance
Solderability	Temperature of Solder : $245 \pm 5^{\circ}C$ Immersion Duration : $2 \pm 0.5$ second Refer to JIS C 5201-1 4.17	Uniform coating of solder cover minimum of 95% surface being immersed
Resistance to Soldering Heat	Dipped into solder at $270 \pm 5^{\circ}C$ for $10 \pm 1$ seconds Refer to JIS C 5201-1 4.18	$\Delta R : \pm (0.5\% + 0.0005\Omega)$ Without distinct deformation in appearance

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Test Item	Condition of Test	Requirements
Load Life	Rated voltage for 1.5 hours followed by a pause 0.5 hour at $70 \pm 2^{\circ}\text{C}$ . Cycle repeated 1000 hours Refer to JIS C 5201-1 4.25	$\Delta R : \pm (1.0\% + 0.0005\Omega)$ Without distinct damage in appearance
Damp Heat with Load	$40 \pm 2^{\circ}\text{C}$ with relative humidity 90% to 95%. D.C. rated voltage for 1.5 hours ON and 30 minutes OFF. Cycle repeated 1,000 hours Refer to JIS C 5201-1 4.24	$\Delta R : \pm (1.0\% + 0.0005\Omega)$ Without distinct damage in appearance
Mechanical Shock	100 G's for 6 milliseconds. 5 pulses Refer to JIS C 5201-1 4.21	$\Delta R : \pm (0.5\% + 0.0005\Omega)$ Without mechanical damage such as break
Bending Test	Glass-Epoxy board thickness : 1.6mm Bending width : 2mm Between the fulcrums : 90mm Refer to JIS C 5201-1 4.33	$\Delta R : \pm (1.0\% + 0.0005\Omega)$ Without mechanical damage such as break

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### 6. Recommended Solder Pad Dimensions



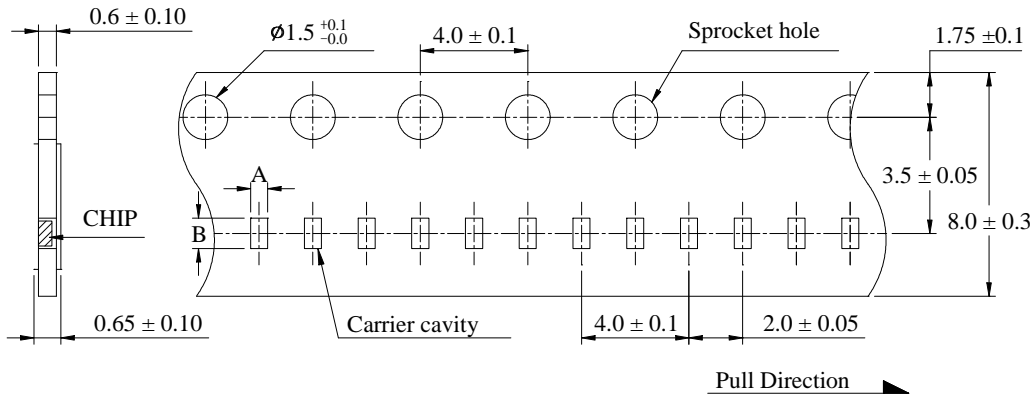
Note : We recommend there is no circuit design between pads to avoid circuit short

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### 7. Packaging

#### 7-1 Dimensions

##### 7-1-1 Tape packaging dimensions

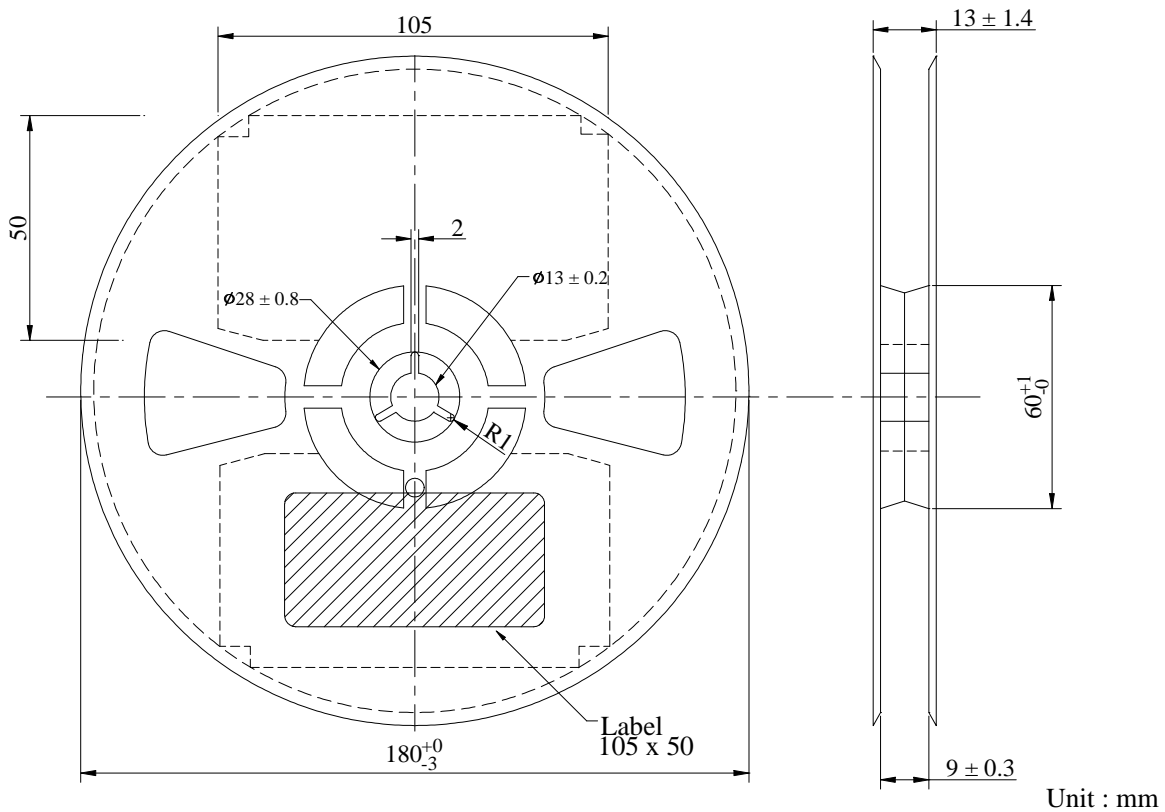


※ Pre-empted holes : 150 holes (or 30cm) or more.

Code letter	A	B
Dimension	$1.45 \pm 0.10$	$2.25 \pm 0.10$

Unit : mm

##### 7-1-2 Reel Dimensions (Plastic reel : Correspond with EIAJ RRV08B)

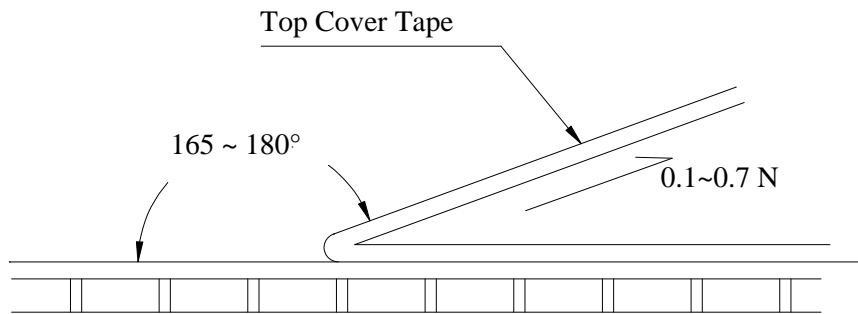


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### 7-2 Peel force of top cover tape

The peel speed shall be about 300 mm / min.

The peel force of top cover tape shall be between 0.1 to 0.7 N.



### 7-3 Numbers of taping

5,000 pieces / reel

### 7-4 Making

The following items shall be marked on the reel.

- (1) Type designation
- (2) Quantity
- (3) Manufacturing date code
- (4) Manufacturer's name
- (5) The country of origin